

as by empirical means. Such methods may also be similarly employed to linearize the reactance response of a wide range of other capacitive force sensor variations that fall within the scope of the invention. Such variations include, for example, complex outlines, nonuniform thickness, flexure in one capacitor plate or both, multiple areas of support or single cantilevered support, etc. In all cases, the desired effect is achieved by shaping the surfaces of one or both capacitor plates to produce a gap that “bottoms out” simultaneously at all points.

[0158] Turning to FIGS. 12A-12D, additional outline and mounting arrangements of force sensor principal elements are shown according to various embodiments of the present invention. All of the elements shown in FIGS. 12A-12D may, for example, be made with uniform thickness. Principal elements 106d, 106e, and 106f provide regions variously narrowed so as to concentrate flexure in areas 1203a-c not serving as capacitor plates. This reduces flexure in capacitive areas 1202a-c, improving linearity of reactance change. Couplings 121d-f receive perpendicular force, which is passed to structures beyond via support areas 1201a-c. With the thicknesses of the principal elements 106d-f being greater, for a given stiffness, than elements of similar size without narrowed regions, clamped support of areas 1201a-c may receive less concentrated twisting stress. Conversely, the concentration of flexure into areas 1203a-c means that simple support of areas 1201a-c will see greater rotation. Couplings 121d-f may be elevated features as described previously, elastic features as described below, or any other coupling feature providing a defined path for entrance of the force to be measured.

[0159] Referring to FIG. 12C, principal element 106f is provided with three areas of support 1201c, whereas principal element 106g (shown in FIG. 12D) is a simple cantilever with a single area of support 1201d. Cantilevered element 106g must, of course, receive clamped support in area 1201d; whereas the other elements 106d-f may be adapted for either simple or clamped support in areas 1201a-c, respectively.

[0160] Turning to FIGS. 13A-13B, additional variations for the cross-sectional shape and thickness of a principal element of a force sensor are shown according to embodiments of the present invention. For example, referring to FIG. 13A, a sensor 1300 is shown according to one embodiment of the present invention. The vertical dimensions of the sensor 1300 (and the sensor 1310, shown in FIG. 13B) are exaggerated approximately tenfold in FIG. 13A with respect to the sensor's horizontal dimensions. Principal element 106h has relatively thin regions 1303 between mounting regions 1301 and capacitive region 1302. These may be produced from planar feedstock by a process such as, for instance, coining. They may again serve to reduce the relative amount of flexure in capacitive area 1302, thereby improving linearity. Referring to FIG. 13B, principal element 106i of sensor 1310 achieves a similar relative stiffening of capacitive region 1302 by laminating this portion. As depicted for principal element 106h, a principal element relatively thicker in support regions 1301 may advantageously reduce stress in the support attachments caused by the moments passing through them.

[0161] Referring to FIGS. 14A-14C, an embodiment of a sensor according to another embodiment of the present

invention is depicted in which the principal element is simply supported, and in which the second element is a discrete element of identical manufacture to the principal element.

[0162] More specifically, turning to FIG. 14A, principal element 106j (shown in solid outline) may be 300 mils wide and may be stamped or photoetched from beryllium-copper 15 mils thick. Tabs 1401a-b engage plastic spacers 1402, allowing principal element 106j to be assembled opposite another identically manufactured element 1403, which, flipped end-for-end with respect to 106j, is inserted into the same pair of spacers 1402.

[0163] FIG. 14B presents a side view of plastic spacer 1402. Rectangular holes 1404a receive tabs 1401a of one element (such as element 106j), while rectangular hole 1404b receives tab 1401b of the opposing element (such as element 1403). Elevations 1405, on the sides of the spacers 1402 away from the principal element 106j, locate the force sensor by engaging holes (not shown) in the support surface. Thus at one end of the force sensor, the support surface corresponds to the plane of 1406a, and at the other, of 1406b.

[0164] FIG. 14C presents a partial cross-section in which principal element 106j and element 1403 are employed as a force sensor in a touch location device. Spacers 1402 are employed above and below the plane of section, and seat against the immediate support surface provided by outer frame 104c. Transparent touch overlay 1408 is secured within the inner frame 1407 by cement 1411. The combination is then supported perpendicularly by plastic force transmission couplings 121h, one of which is associated with each sensor. Couplings 121h may be press fit into holes in inner frame 1407, which align over the centers of the square capacitive areas afforded by each of the principal elements 106j employed. Inner frame 1407 is supported laterally by combination seal and lateral restraint means 1409. Oversize clearance holes may be provided in inner frame 1407, if necessary, to guarantee that there is no contact with the unused elevations 1405 that are on the surfaces of spacers 1402 directed upward. Discrete wiring 1410 may connect to the upper surfaces of tabs 1401 by soldering or wire welding. Application bezel 1412 seats against lateral restraint means 1409 and frame 104c.

[0165] When unloaded, principal element 106j rests about 10 mils above the surface of non-flexing element 1403. Holes 1404a-b are somewhat larger at the surface of spacer 1402, and taper to minimal cross-section at its center, which cross-section just matches tabs 1401a-b. Thus as force is applied to coupling 121h, principal element 106j flexes as a member having simply-supported end constraint with minimal friction.

[0166] The arrangement of FIG. 14C offers a touch location device of minimal thickness, but the inclusion of inner frame 1407 increases border width. The sensor is scalable to other, including smaller, sizes.

[0167] Since principal element 106j may be located quite close to the plane of touch, special provisions for handling tangential forces may be omitted without significant adverse consequences. For instance, the aggregate lateral stiffness of lateral restraint means 1409 need not substantially exceed the aggregate lateral stiffness of the force sensors and their